# The Digital Abstraction

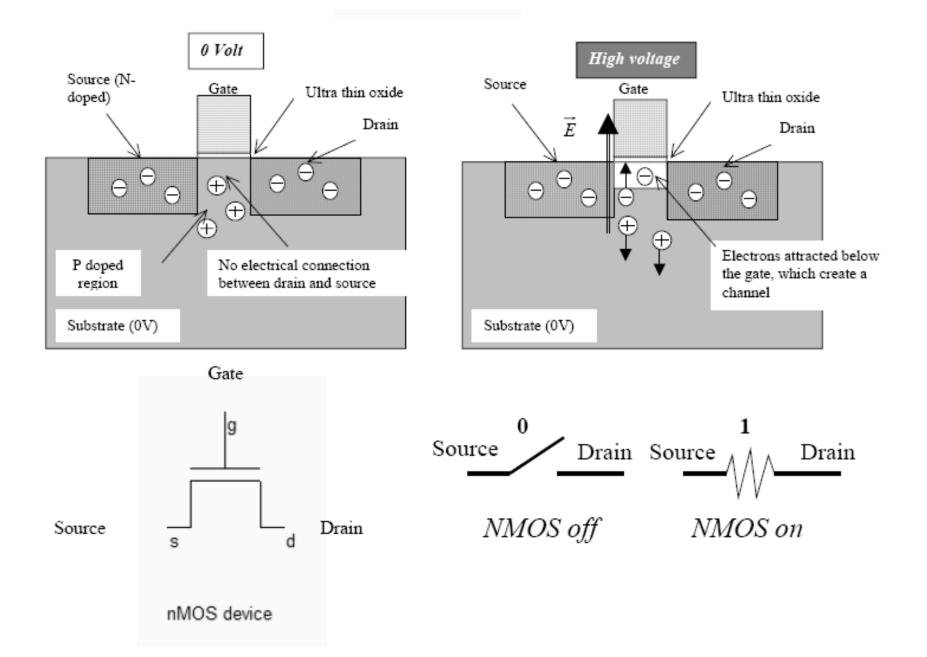
Andreas G. Andreou



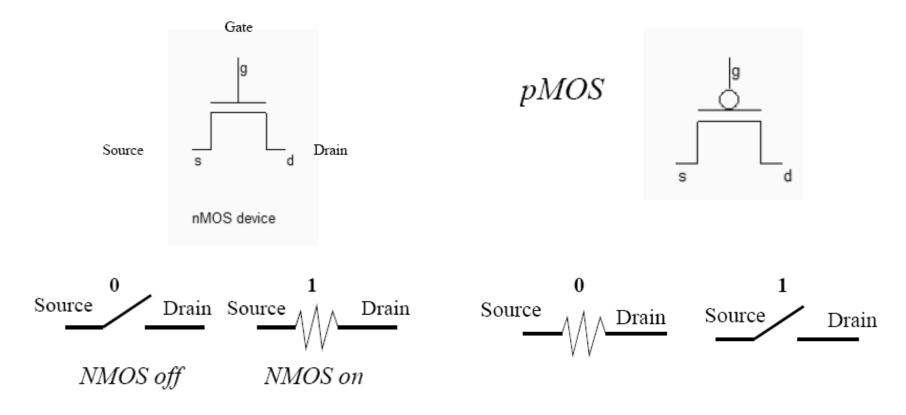
# logic levels definitions

Logical value	Voltage	Name	Symbol in DSCH	Symbol in Microwind
0	0.0V	VSS	77777 (Green in logic simulation)	f (Green in analog simulation)
1	1.2V in emos 0.12μm	VDD	(Red in logic simulation)	(Red in analog simulation)
Х	Undefined	Х	(Gray in simulation)	(Gray in simulation)

# **MOS transistor**



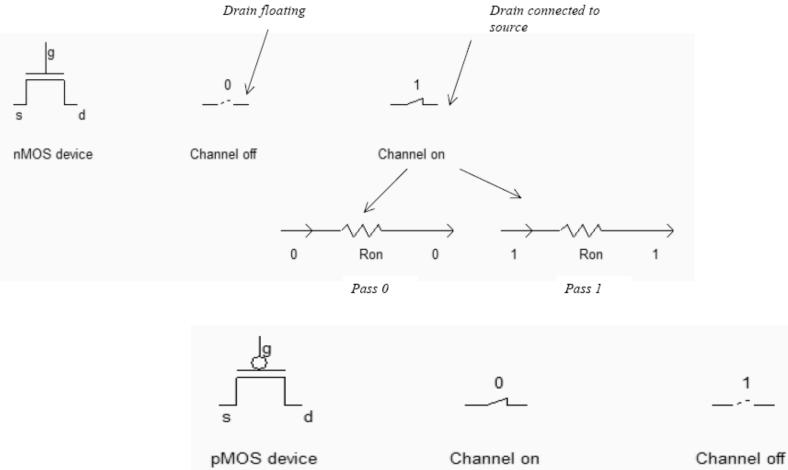
# NMOS and PMOS digital "models"

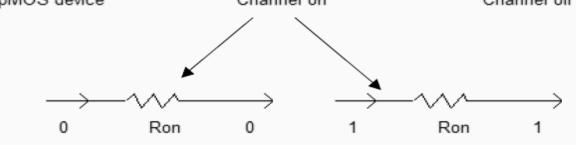


Gate	Source	Drain
0	0	Х
0	1	Х
1	0	0
1	1	1

Gate	Source	Drain
0	0	0
0	1	1
1	0	Х
1	1	Х

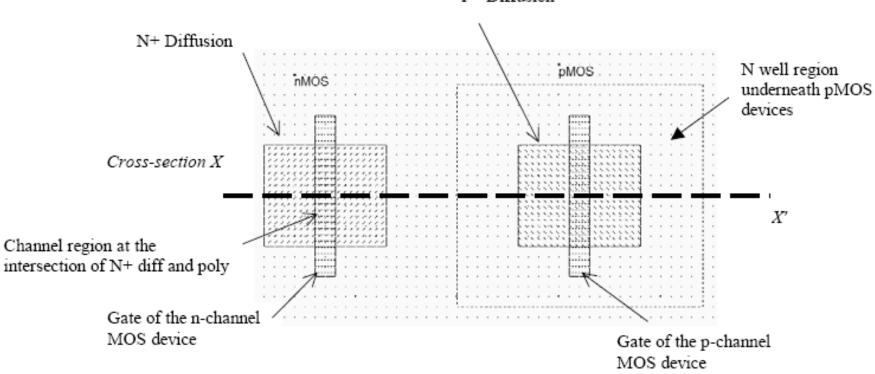
# what does this all mean?





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### and back to layout



P+ Diffusion

Figure 2-14: Bird's view of the n-channel and p-channel MOS device layout (allMosDevices.MSK)

#### cross-section and zoom

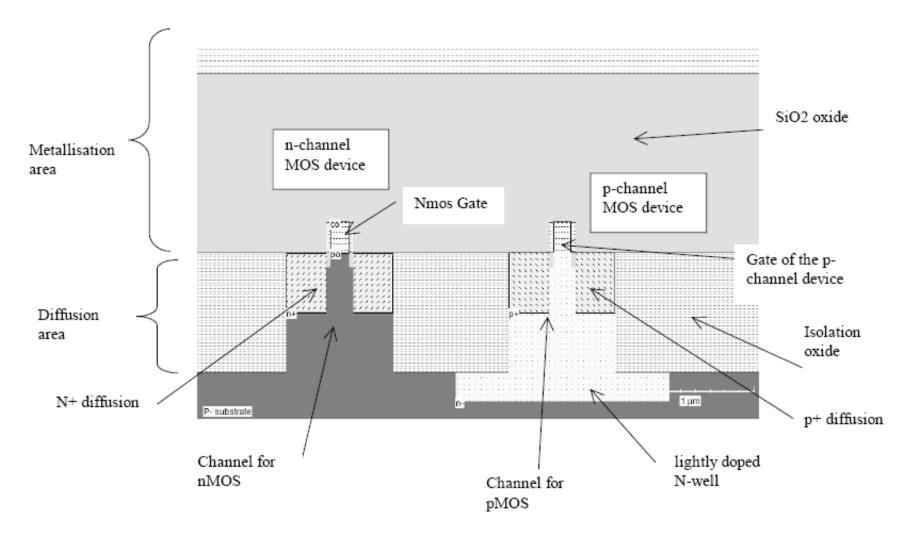
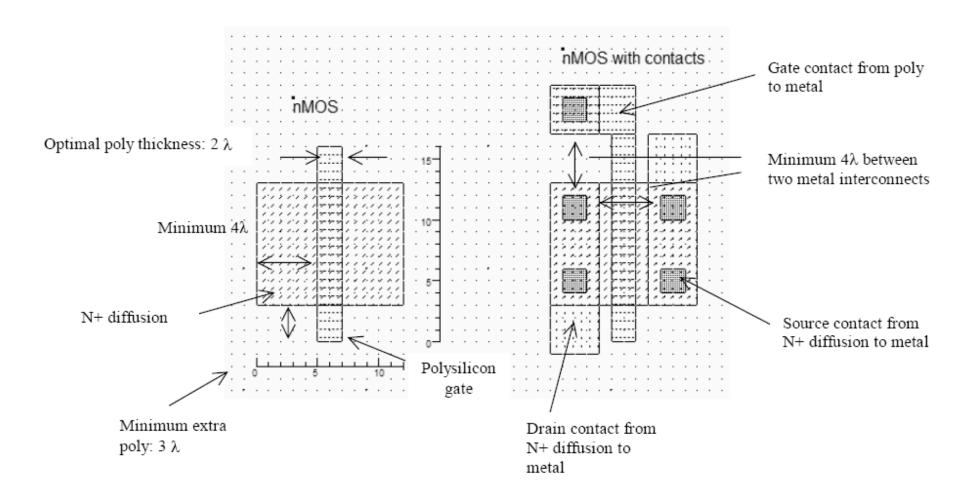
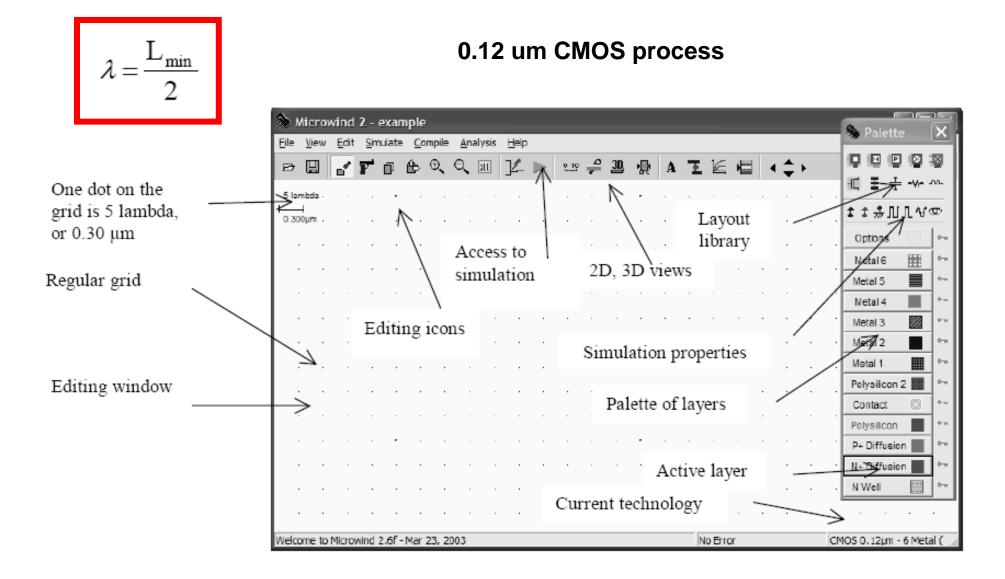


Figure 2-15: Vertical cross-section of an n-channel and p-channel MOS devices in 0.12µm technology

# **MOS transistor layout**



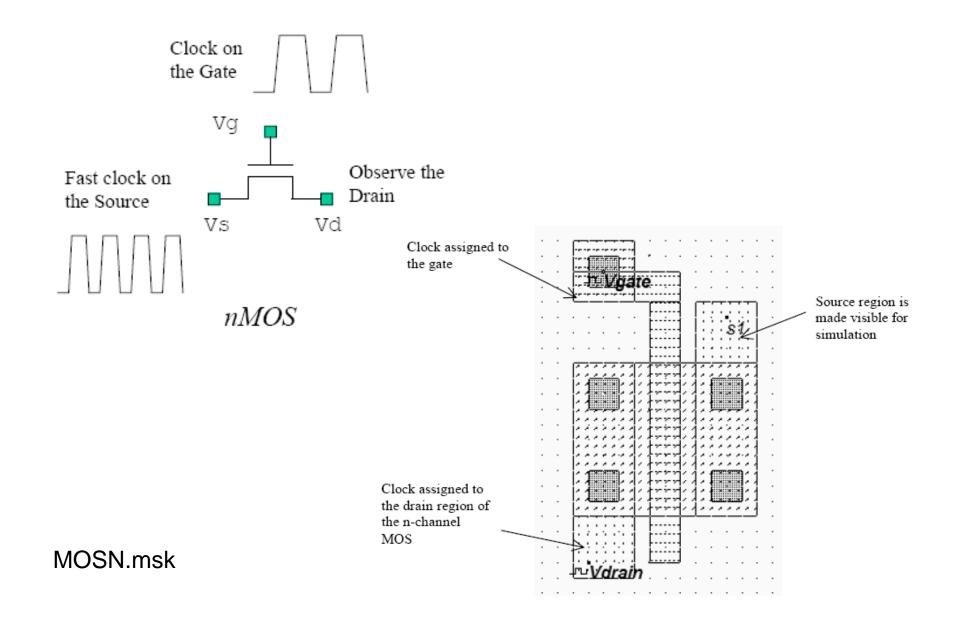
# microwind



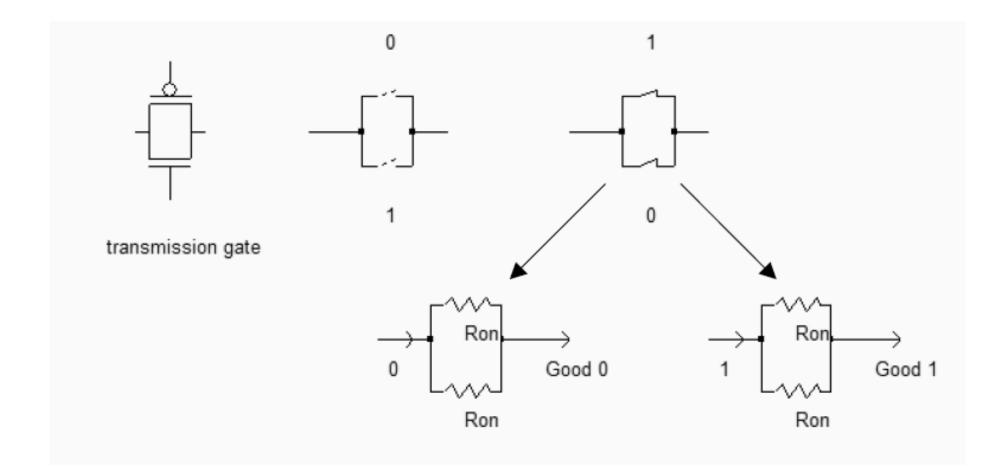
#### more notation

Layer name	Code	Description	Color in Microwind
Polysilicon	Poly	Gate of the n-channel and p-channel MOS devices	Red
N+ diffusion	Diffn	Delimits the active part of the n-channel device. Also used to polarize the N-well	Dark green
P+ diffusion	Diffn	Delimits the active part of the p-channel device. Also used to polarize the bulk	Maroon
Contact	Contact	Makes the connection between diffusions and metal for routing. The contact plug is fabricated by drilling a hole in the oxide and filling the hole with metal.	
First level of metal	Metal1	Used to rout devices together, in order to create the logic or analog function	Blue
N well	Nwell	Low doped diffusion used to invert the doping of the substrate. All p-channel MOS are located within N well areas.	c

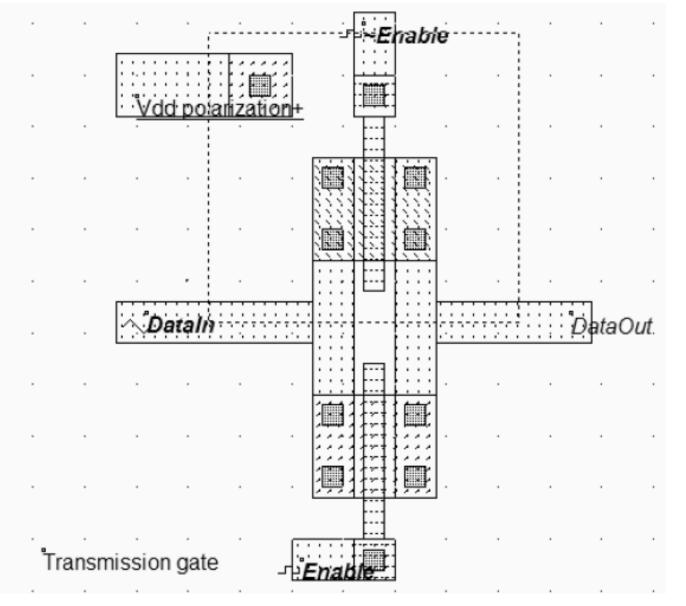
#### dynamic behavior: another level of abstraction



### and the perfect switch!



### simulation of the perfect switch



TGATE.msk

### multiple contacts: why?

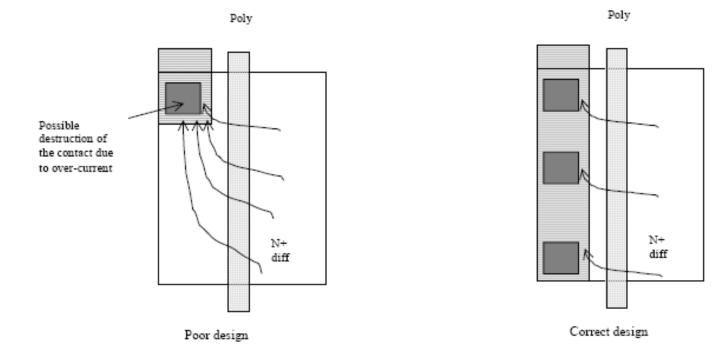


Fig.2-46. A strong current through a single contact could damage the metal structure.

# multiple contacts

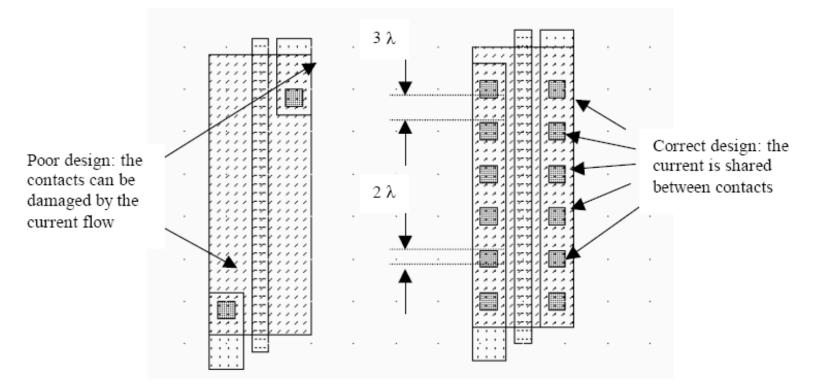


Fig.2-47. A single contact cannot handle more that 1mA. A series of contacts is preferred (MosLayout.MSK)

### multiple contacts

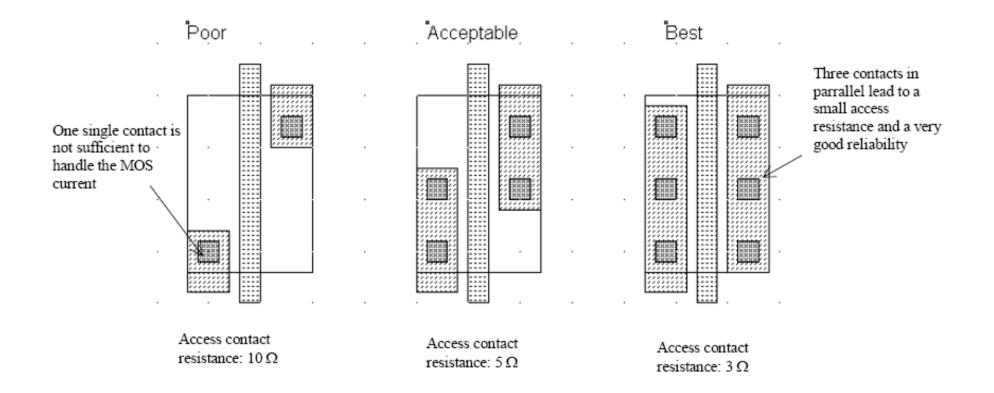


Fig.2-48. A series of contacts also reduced the serial access resistance(MosContacts.MSK)

# multiple gates

